

DOCKET NO. 99-102/1D



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: : Wilbur G. Catabay and Richard Schinella

Appl. No. : 10/099,641

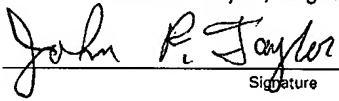
Filed: : March 15, 2002

Title : LOW K DIELECTRIC COMPOSITE LAYER FOR INTEGRATED
CIRCUIT STRUCTURE WHICH PROVIDES VOID-FREE LOW K
DIELECTRIC MATERIAL BETWEEN METAL LINES WHILE
MITIGATING VIA POISONING

Grp./ A.U. : 2829

Examiner : Lisa A. Kilday

Docket No. : 99-102/1D

CERTIFICATE OF MAILING	
I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231	
on	April 2, 2003 (Date of Deposit)
John P. Taylor, Reg. No. 22,369	
	 Signature
	April 2, 2003 Date of Signature

AMENDMENT

Honorable Commissioner for Patents
Washington, D.C. 20231

Sir:

Date: April 2, 2003

In response to the Office Action mailed January 31, 2003, please amend the application as follows:

#7/Amat B
4.11.03
C Moore

RECEIVED
APR 10 2003
TECHNOLOGY CENTER 2800